

ABSTRACT

PROTECTIVE FILM FORMING METHOD

Disclosed herein is a protective film forming method for forming a protective film of a water-soluble resin on the front side of a wafer having a plurality of devices on the front side. The wafer is supported through an adhesive tape to an annular frame. The protective film forming method includes a water-soluble resin removing step of removing the water-soluble resin scattered onto the upper surface of the annular frame in forming the protective film on the front side of the wafer held on a spinner table. The water-soluble resin removing step includes the steps of rotating the spinner table, positioning a cleaning water nozzle above the upper surface of the annular frame held on the spinner table, supplying a cleaning water from the cleaning water nozzle to the upper surface of the annular frame, positioning an air nozzle adjacent to the cleaning water nozzle on the downstream side thereof in the rotational direction of the spinner table, and supplying air from the air nozzle against the flow of the cleaning water on the upper surface of the annular frame, whereby the cleaning water is forced to temporarily stay on the upper surface of the annular frame by the air supplied and is then expelled outward of the annular frame.

(Figure 8A)